

Press

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SMT Hybrid Packaging 2017
International Exhibition and Conference
for System Integration in Micro Electronics
Nuremberg, Germany, 16 – 18 May 2017

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SMT Hybrid Packaging 2017: New hall occupation and additional joint stand

At the SMT Hybrid Packaging visitors experience the diversity of assembly and interconnection technologies in a new setting at the well-established exhibition site in Nuremberg this year: The International Exhibition and Conference for System Integration in Micro Electronics will take place 16 – 18 May 2017 in the halls 4, 4A and 5. As usual, the hall main topics are structured along the value chain to offer an ideal orientation to the visitors:

- In **hall 5**, the topics “System Development and Production Preparation” as well as “Materials and Components” will be presented.
- In **hall 4**, the visitors will find all about “Processes and Manufacturing”.
- The new **hall 4A** showcases the topics “Reliability and Test” and “Software and Production Control”.

“Cluster Mechatronik & Automation“ represented for the first time

The Bavarian cluster “Mechatronik & Automation” is present with a joint stand at the SMT Hybrid Packaging 2017 for the first time.

The Cluster wants to push an active communication between research and industry. Therefore, the non-profit organization in the field of technical business support as well as technology and knowledge transfer has created and developed several networks for purchasing SMD components, marketing surplus components, and capacity balancing between EMS companies in the last few years.

“Although we decided to participate at SMT rather late, we are able to offer a joint stand in Nuremberg this year for the first time, which we will step up gradually in the coming years”, explains Tom Weber manager of the Cluster. The target is to offer a reliable and future oriented platform.

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Co-exhibitors of the Cluster in hall 4 are e.g. Rohde & Schwarz, a specialist for complex PCBs and sophisticated manufacturing services as well as representatives of the Fraunhofer EMFT as experts for packaging technologies. Moreover, the company optical control GmbH & Co. KG is represented at the joint stand.

SMT Hybrid Packaging is the only event in Europe which takes a comprehensive view of system integration in microelectronics, from the initial idea and its development right through to the production of all technical processes during the manufacture of electronic assemblies. Visitors find tailored knowledge and individual solutions for their daily needs.

Interested persons can register on the website smthybridpackaging.com/tickets for a free day ticket and find detailed information about the event.

About Mesago

Mesago, founded in 1982 and located in Stuttgart, specializes in exhibitions and conferences on various topics of technology. The company belongs to the Messe Frankfurt Group. Mesago operates internationally and is not tied to a specific venue. With 130 members of staff Mesago organizes events for the benefit of more than 3,300 exhibitors and over 110,000 trade visitors, conference delegates and speakers from all over the world. Numerous trade associations, publishing houses, scientific institutes and universities work with Mesago closely as advisers, co-organizers and partners. Mesago comprises three companies: Mesago Messe Frankfurt GmbH, Mesago Messemanagement GmbH and Mesago PCIM GmbH.
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